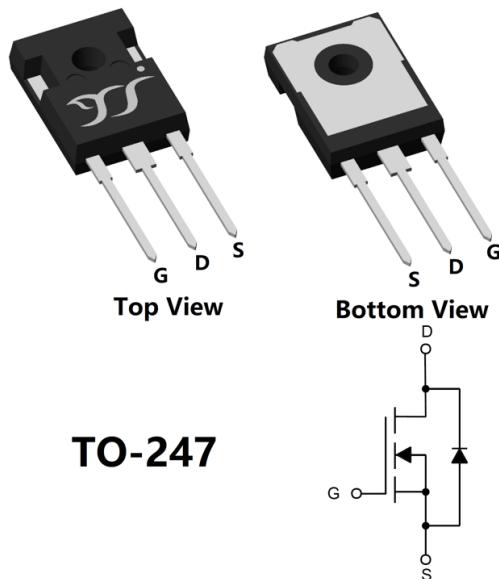




## N-Channel Enhancement Mode Field Effect Transistor



### Product Summary

- $V_{DS}$  200V
- $I_D$  98A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ )  $<11.5m\Omega$
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- UPS and Inverter applications
- Motor drivers
- DC-DC convertor

### ■ Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit	
Drain-source Voltage	$T_A=25^\circ C, V_{GS}= 10V$	$T_A=100^\circ C, V_{GS}= 10V$	$V_{DS}$	-	200	V	
Gate-source Voltage			$V_{GS}$	-20	20		
Continuous Drain Current (Note 1,2)			$I_D$	-	10.5		
Continuous Drain Current (Note 1,3)			$I_D$	-	6.6		
Pulsed Drain Current	$T_C=25^\circ C, t_p \leq 10\mu s$		$I_{DM}$	-	392	A	
Maximum Body-Diode Continuous Current	$T_C=25^\circ C$		$I_S$	-	98		
Avalanche energy (non-repetitive )	$T_J=25^\circ C, V_G=10V, R_G=25\Omega, L=0.5mH, IAS=50A$		EAS	-	625	mJ	
Total Power Dissipation (Note 1,2)	$T_A=25^\circ C$	$T_A=100^\circ C$	$P_D$	-	2.97		
Total Power Dissipation (Note 1,3)		$T_C=25^\circ C$	$P_D$	-	1.19		
Junction and Storage Temperature Range	$T_J, T_{STG}$		$T_J, T_{STG}$	-55	150	°C	

### ■ Thermal Resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	$R_{\theta JA}$	-	42	°C/W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	0.48	

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJW012G20H	B1	YJW012G20H	30	360	1800	Tube



# YJW012G20H

## ■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA, T <sub>j</sub> =25°C	200	-	-	V
		V <sub>GS</sub> =0V, I <sub>D</sub> =1mA, T <sub>j</sub> =25°C	200	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =200V, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C	-	-	1	μA
		V <sub>DS</sub> =200V, V <sub>GS</sub> =0V, T <sub>j</sub> =125°C	-	-	100	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V, T <sub>j</sub> =25°C	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA, T <sub>j</sub> =25°C	2.2	3	3.8	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A, T <sub>j</sub> =25°C	-	9.7	11.5	mΩ
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =50A, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C	-	0.86	1.2	V
Gate Resistance	R <sub>G</sub>	f=1MHz, T <sub>j</sub> =25°C	-	0.8	-	Ω
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, f=1MHz, T <sub>j</sub> =25°C	-	3920	-	pF
Output Capacitance	C <sub>oss</sub>		-	445	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	11.3	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =100V, I <sub>D</sub> =50A, T <sub>j</sub> =25°C	-	50.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	18.4	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	8.2	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =50A, di/dt=100A/μs, V <sub>GS</sub> =0V, V <sub>R</sub> =100V, T <sub>j</sub> =25°C	-	513	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	135	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =100V, I <sub>D</sub> =50A, R <sub>GEN</sub> =3Ω, T <sub>j</sub> =25°C	-	20	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	42	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	32	-	
Turn-off Fall Time	t <sub>f</sub>		-	9	-	

Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of R<sub>θJA</sub> is measured in the still air environment with T<sub>A</sub>=25°C. The maximum allowed junction temperature of 150°C.
- Thermal resistance from junction to soldering point (on the exposed drain pad).



**YJW012G20H**

■ Typical Electrical and Thermal Characteristics Diagrams

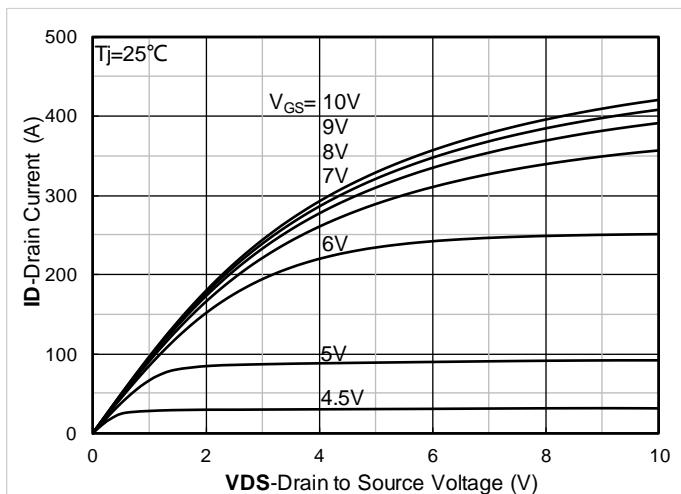


Figure 1. Output Characteristics; typical values

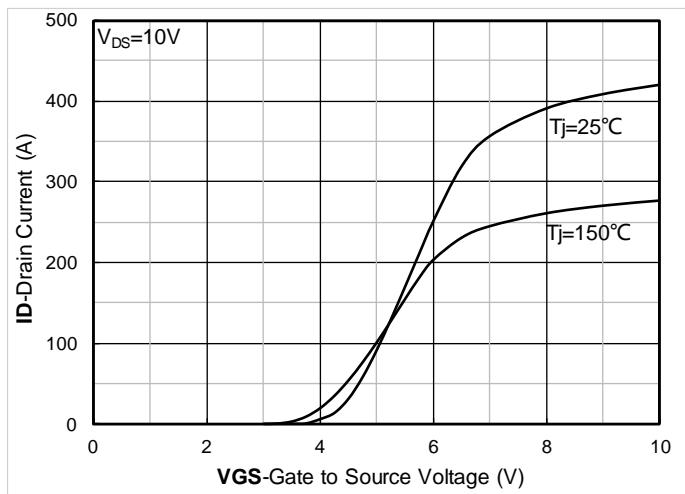


Figure 2. Transfer Characteristics; typical values

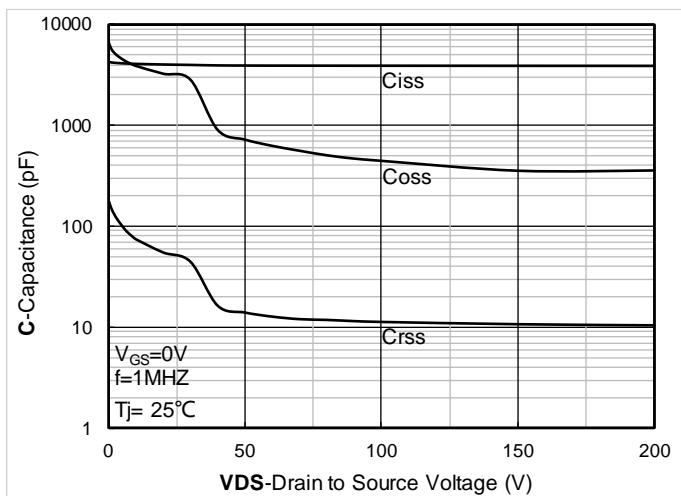


Figure 3. Capacitance Characteristics; typical values

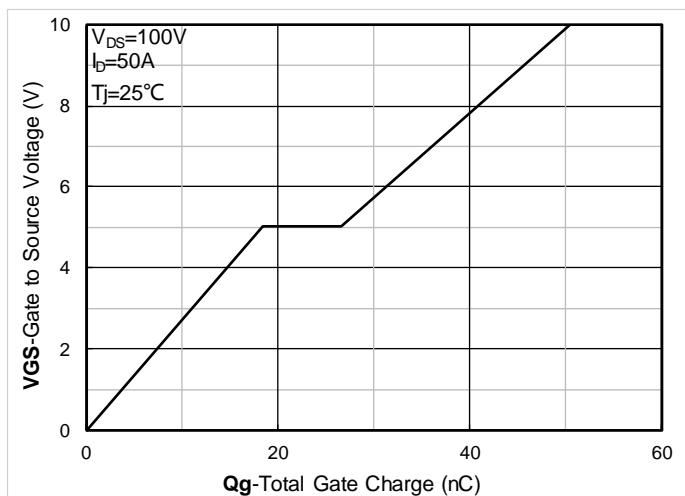


Figure 4. Gate Charge; typical values

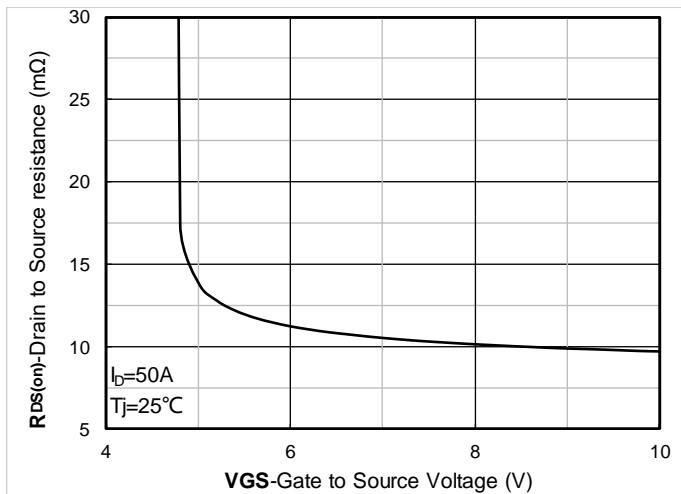


Figure 5. On-Resistance vs Gate to Source Voltage; typical values

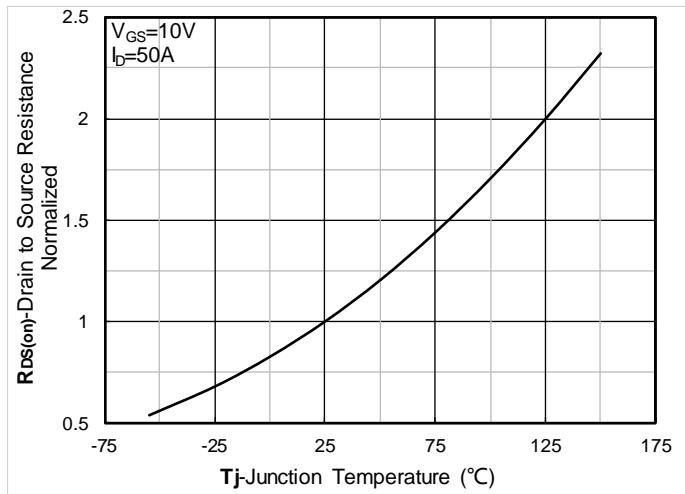


Figure 6. Normalized On-Resistance



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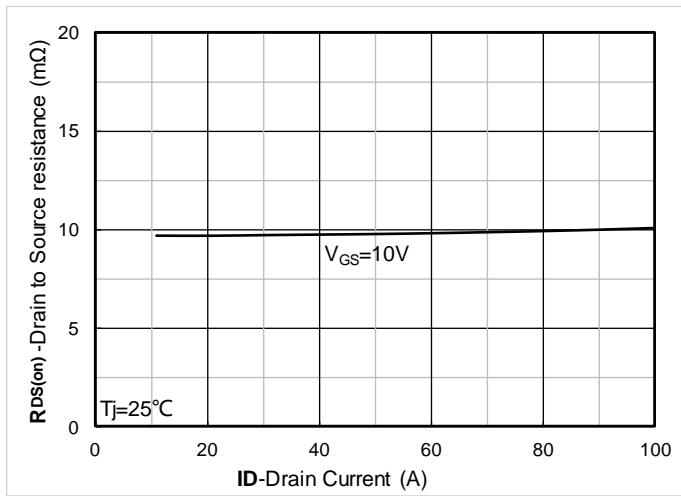


Figure 7. RDS(on) VS Drain Current; typical values

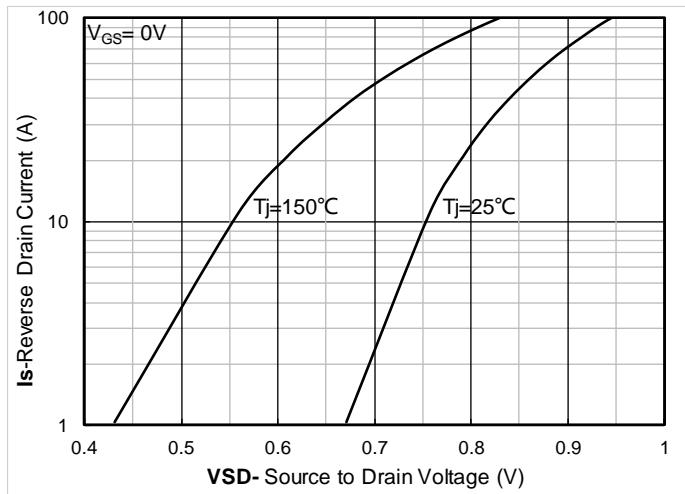


Figure 8. Forward characteristics of reverse diode; typical values

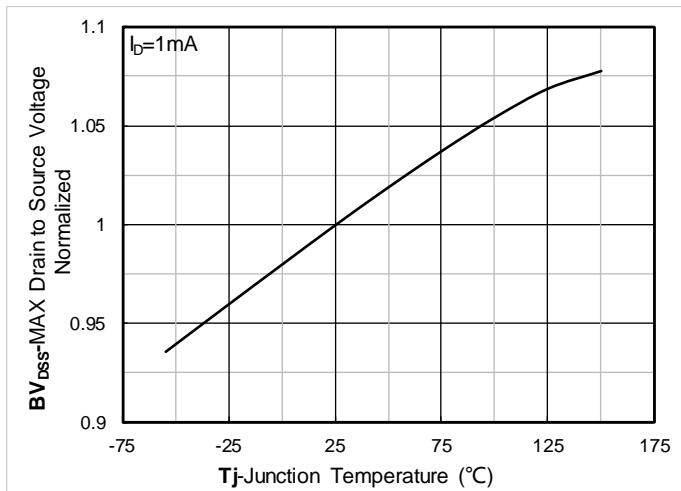


Figure 9. Normalized breakdown voltage

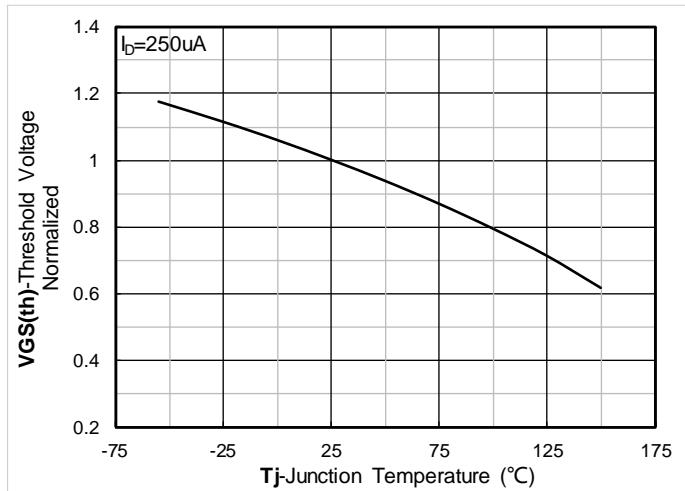


Figure 10. Normalized Threshold voltage

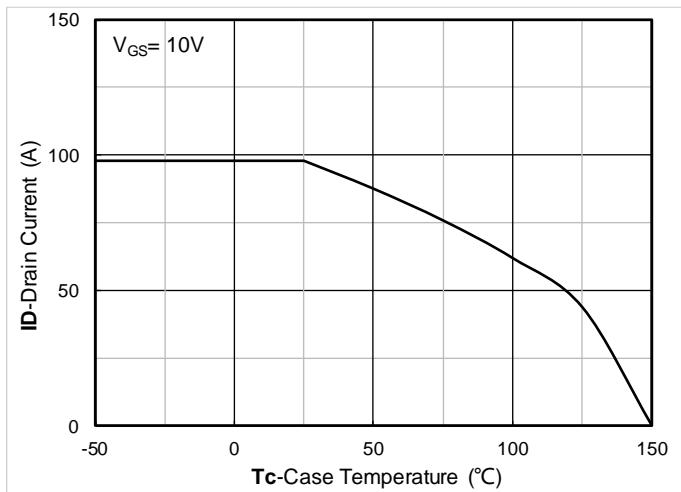


Figure 11. Current dissipation

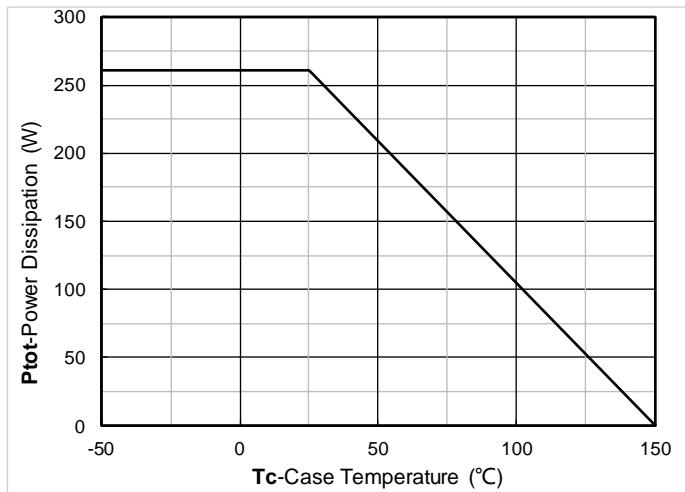


Figure 12. Power dissipation

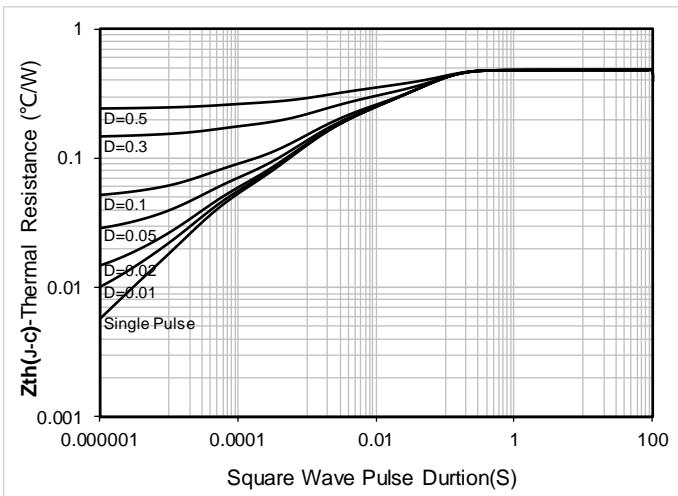


Figure 13. Maximum Transient Thermal Impedance

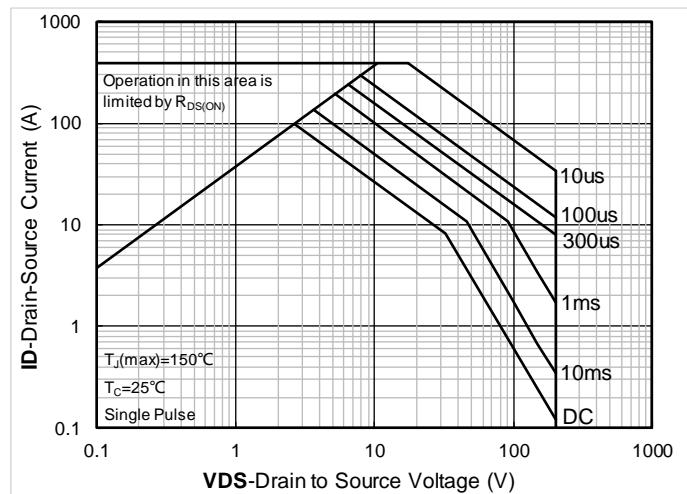


Figure 14. Safe Operation Area

## ■ Test Circuits & Waveforms

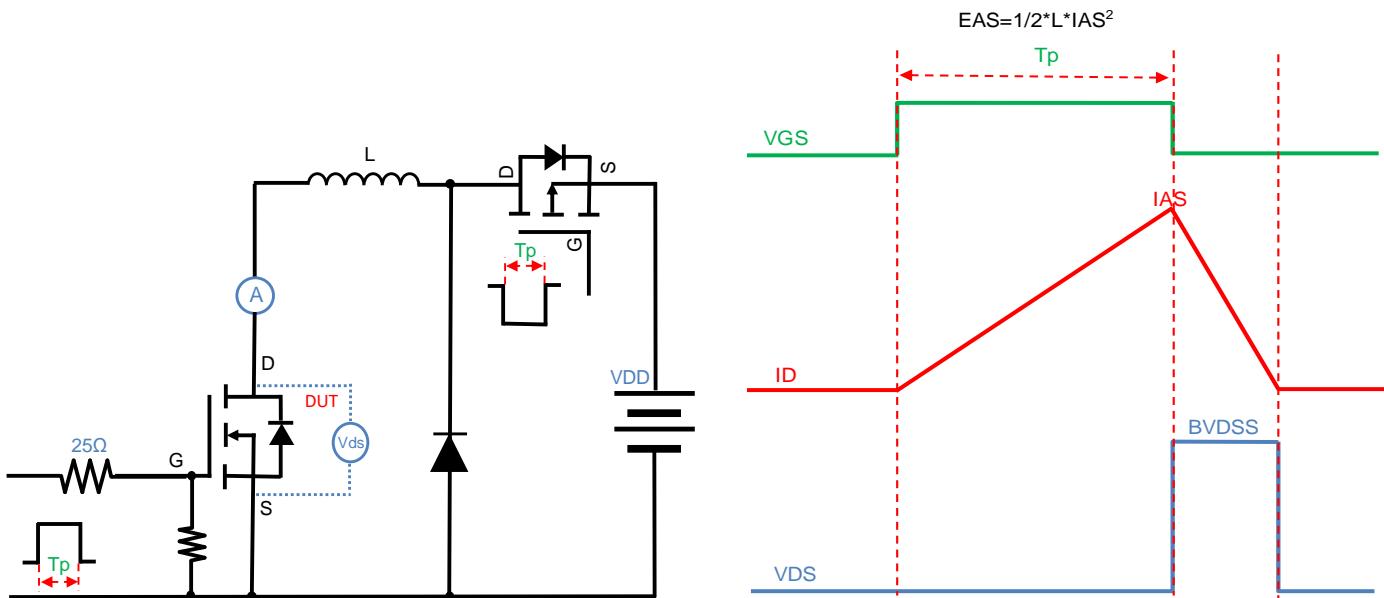


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

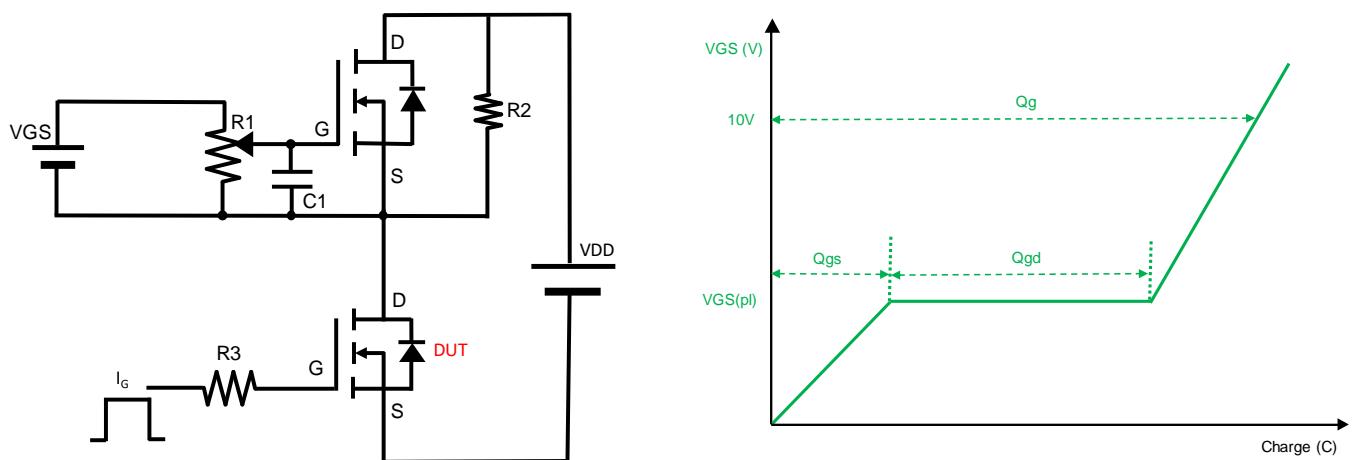


Figure B. Gate Charge Test Circuit & Waveform

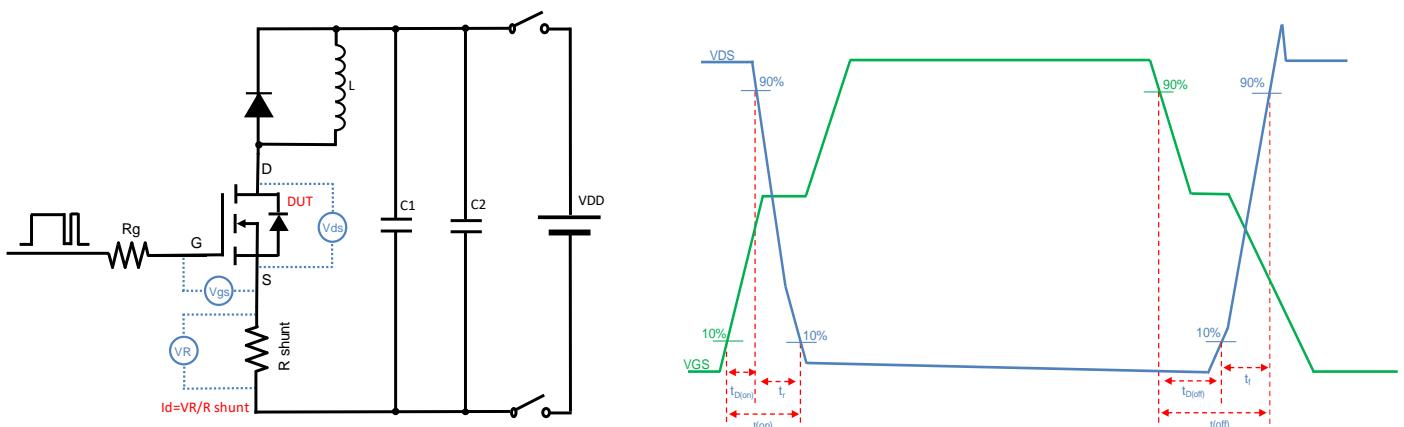


Figure C. Resistive Switching Test Circuit & Waveform

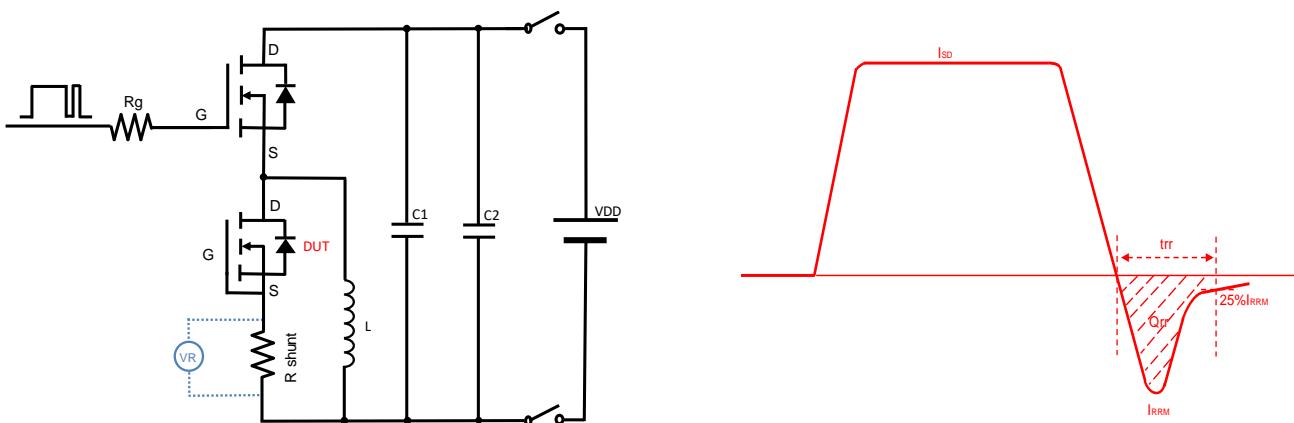
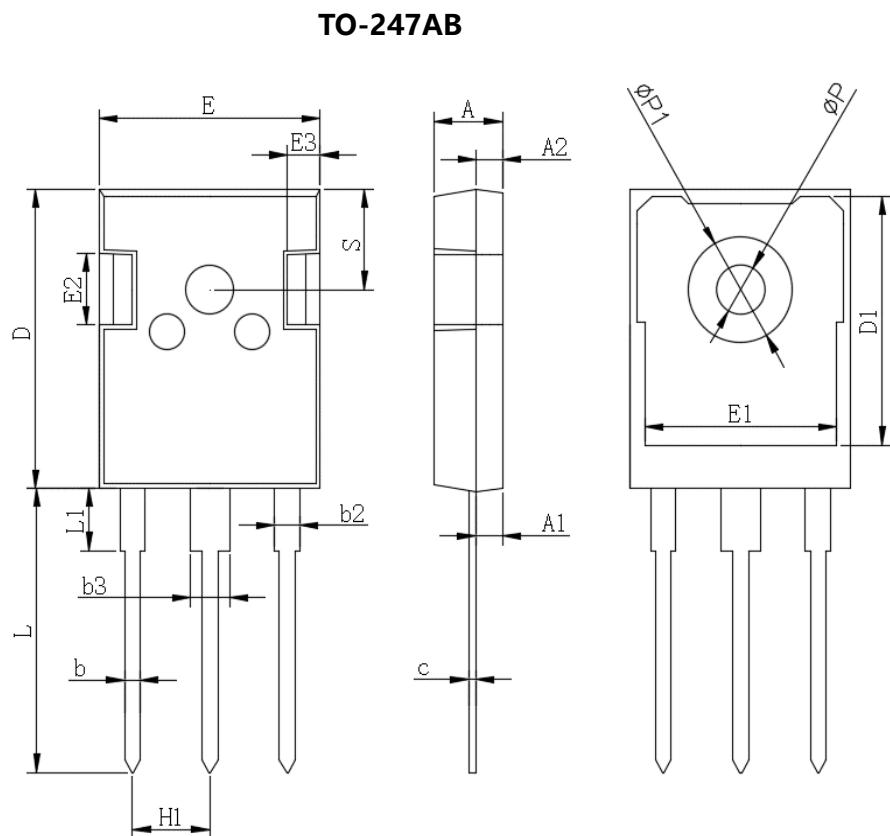


Figure D. Diode Recovery Test Circuit & Waveform



## ■ TO-247AB Package information



TO-247AB		
Dim	Min	Max
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.0	1.4
b2	1.91	2.21
c	0.5	0.7
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.0	13.6
E2	4.80	5.20
E3	2.30	2.70
L	19.62	20.22
L1	-	4.30
ΦP	3.40	3.80
ΦP1	-	7.30
S	6.15TYP	
H1	5.44TYP	
b3	2.80	3.20



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